Material Composition Specification

Case CM

Device average mass . . . . 3.0 g
Fluctuation margin . . . . +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	0.52%	15.59	Si	7440-21-3	0.51%	15.56	5,187
				Au	7440-57-5	0.01%	0.03	10
leadframe	copper	36.64%	1,099	Cu	7440-50-8	36.64%	1,099	366,353
die attach	high temperature solder	0.45%	13.61	Pb	7439-92-1	<0.001%	0.002	1
				Sn	7440-31-5	0.45%	13.608	4,536
encapsulation	EMC	60.83%	1,825	epoxy resin	Proprietary	60.83%	1,825	608,333
plating*	tin/lead process	1.56%	46.74	Sn	74401-31-5	1.25%	37.40	12,464
				Pb	7439-92-1	0.31%	9.34	3,116
	matte tin	1.56%	46.74	Sn	7440-31-5	1.56%	46.74	15,580

*For Lead Free plating, add suffix “PB FREE” to part number.
For Tin/Lead plating, add suffix “TIN/LEAD” to part number.
No suffix designation allows for the supply of either lead-free or tin/lead plated product depending on availability.

Disclaimer
The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.